

Part Number: **UMCxN-p, UMGxN-p**
Weight (mg): 6.1396

p = package designator x=4,5
See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	3.04	0.1866	1000000	30393
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	28.68	1.7607	576500	165327
		Ni	7440-02-0	41.00%			410000	117579
		Mn	7439-96-5	0.60%			6000	1721
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	287
		Co	7440-48-4	0.50%			5000	1434
		Si	7440-21-3	0.15%			1500	430
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.00	0.0611	1000000	9952
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.41	0.0252	1000000	4105
Encapsulation	CEL-1702HF-9	Silica	60676-86-0	87.30%	61.50	3.7756	873000	536859
		Basic Duromer: Epoxy resin (Compound of a polymeric network)	----	5.00%			50000	30748
		Basic Duromer: Phenolic resin (Compound of polymeric network)	----	5.00%			50000	30748
		Misc. system	system	2.50%			25000	15374
		Carbon black	1333-86-4	0.20%			2000	1230
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	5.38	0.3304	1000000	53815
					Total	100.00	6.1396	1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, [Material Composition Declaration for Electronic Products](#).

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Organic tin compounds
Antimony Compounds	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBD
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Dimethyl fumarate	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Halogens	Radioactive Substances
Hexavalent chromium compounds	Red Phosphorous
Lead and lead compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Mercury and mercury compounds	Tributyl Tin Oxide (TBTO)
REACH SVHCs and other Substances of Concern:	5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Anthracene	Bis (2-ethyl(hexyl)phthalate) (DEHP)
4,4'- Diaminodiphenylmethane	Hexabromocyclododecane (HBCDD)
Dibutyl phthalate	Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Cyclododecane	Bis(tributyltin)oxide
Cobalt dichloride	Lead hydrogen arsenate
Diarsenic pentaoxide	Triethyl arsenate
Diarsenic trioxide	Benzyl butyl phthalate
Sodium dichromate, dihydrate	
Beryllium, Beryllium Alloys and Compounds	Methylene Chloride
Hydrazine	Trichloroethene
Tetrachloroethylene	Methyl Ethyl Ketone
Toluene	Xylenes
Toluene Diisocyanate	